

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS6591104DA2NMA	Active	Production	NFBGA (NMA) 98	240 JEDEC TRAY (5+1)	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	6591104DA2NMA
TPS6591104DA2NMA.A	Active	Production	NFBGA (NMA) 98	240 JEDEC TRAY (5+1)	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	6591104DA2NMA
TPS6591104DA2NMA.B	Active	Production	NFBGA (NMA) 98	240 JEDEC TRAY (5+1)	-	Call TI	Call TI	-40 to 85	
TPS659110A2NMAR	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	659110A2NMA
TPS659110A2NMAR.A	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	659110A2NMA
TPS659110A2NMAR.B	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	-	Call TI	Call TI	-40 to 85	
TPS659110A2ZRC	Obsolete	Production	BGA MICROSTAR JUNIOR (ZRC) 98	-	-	Call TI	Call TI	-	TPS659110A2
TPS659112A2NMAR	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	659112A2NMA
TPS659112A2NMAR.A	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	659112A2NMA
TPS659112A2NMAR.B	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	-	Call TI	Call TI	-40 to 85	
TPS659112A2ZRC	Obsolete	Production	BGA MICROSTAR JUNIOR (ZRC) 98	-	-	Call TI	Call TI	-	TPS659112A2
TPS6591133A2NMA	Active	Production	NFBGA (NMA) 98	240 JEDEC TRAY (5+1)	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	6591133A2NMA
TPS6591133A2NMA.A	Active	Production	NFBGA (NMA) 98	240 JEDEC TRAY (5+1)	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	6591133A2NMA
TPS6591133A2NMA.B	Active	Production	NFBGA (NMA) 98	240 JEDEC TRAY (5+1)	-	Call TI	Call TI	-40 to 85	
TPS659114A2NMAR	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	659114A2NMA
TPS659114A2NMAR.A	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	659114A2NMA
TPS659114A2NMAR.B	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	-	Call TI	Call TI	-40 to 85	
TPS659114A2ZRCT	Obsolete	Production	BGA MICROSTAR JUNIOR (ZRC) 98	-	-	Call TI	Call TI	-	659114A2
TPS659118A2ZRCT	Obsolete	Production	BGA MICROSTAR JUNIOR (ZRC) 98	-	-	Call TI	Call TI	-	659118A2
TPS65911AA2NMAR	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	65911AA2NMA
TPS65911AA2NMAR.A	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	65911AA2NMA
TPS65911AA2NMAR.B	Active	Production	NFBGA (NMA) 98	2500 LARGE T&R	-	Call TI	Call TI	-40 to 85	

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS65911AA2NMAT	Active	Production	NFBGA (NMA) 98	250 SMALL T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	65911AA2NMA
TPS65911AA2NMAT.A	Active	Production	NFBGA (NMA) 98	250 SMALL T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	65911AA2NMA
TPS65911AA2NMAT.B	Active	Production	NFBGA (NMA) 98	250 SMALL T&R	-	Call TI	Call TI	-40 to 85	

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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